超微細配線対応硫酸銅めっき添加剤

Additives for Acid Copper Plating for Ultra Fine Pattern

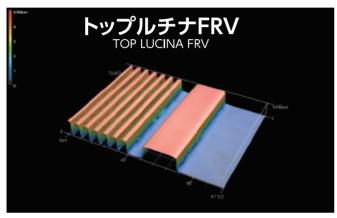
トップルチナFRV

TOP LUCINA ERV

- パターン幅にかかわらず、良好な矩形配線を実現 Regardless of pattern size/density, square-shape patterns can be obtained
- 高い膜厚均一性 (L/S = 2/2 μm対応) Uniform thickness is available (Applicable to line / space = 2/2 μm)
- ・微小ビア(ビア径10 μm)のフィリングに対応 Micro-via filling is possible (Hole diameter: 10 μm)

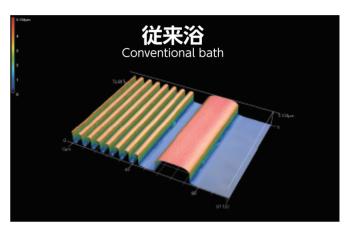
良好な矩形配線

Square-shape patterns can be obtained





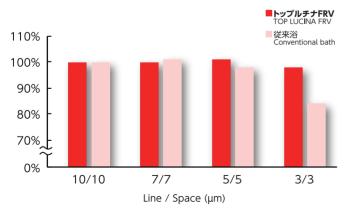
矩形性 **4.9**% Square-shape ratio





矩形性 20.2% Square-shape ratio

高い膜厚均一性 Excellent in thickness uniformity



Line / Spaceと膜厚の関係 Relationship of line /space and film thickness (L/S=10/10 μmのときの膜厚を100%とする) Set the film thickness at L/S=10/10 μm as 100%

微小ビアのフィリングに対応 Micro-via filling is possible

微小ビア(φ10 μm) 断面観察像 Cross section image of micro-via (Hole diameter: 10 μm)

